

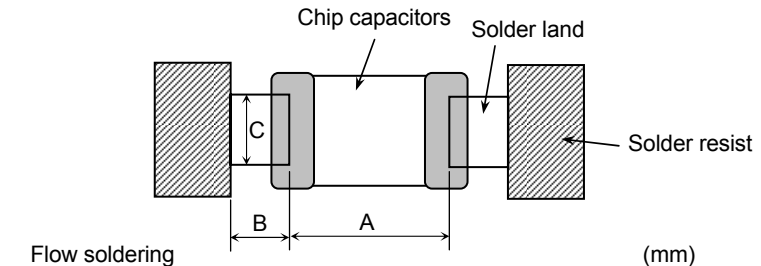
(a)

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Designing P.C.board

The amount of solder at the terminations has a direct effect on the reliability of the capacitors.

- 1) The greater the amount of solder, the higher the stress on the chip capacitors, and the more likely that it will break. When designing a P.C.board, determine the shape and size of the solder lands to have proper amount of solder on the terminations.
- 2) Avoid using common solder land for multiple terminations and provide individual solder land for each terminations.
- 3) Size and recommended land dimensions.



Flow soldering		(mm)		
Type	Symbol	C1608 (CC0603)	C2012 (CC0805)	C3216 (CC1206)
A		0.7 - 1.0	1.0 - 1.3	2.1 - 2.5
B		0.8 - 1.0	1.0 - 1.2	1.1 - 1.3
C		0.6 - 0.8	0.8 - 1.1	1.0 - 1.3

Reflow soldering		(mm)				
Type	Symbol	C0402 (CC01005)	C0603 (CC0201)	C1005 (CC0402)	C1608 (CC0603)	C2012 (CC0805)
A		0.15 - 0.25	0.25 - 0.35	0.3 - 0.5	0.6 - 0.8	0.9 - 1.2
B		0.15 - 0.25	0.2 - 0.3	0.35 - 0.45	0.6 - 0.8	0.7 - 0.9
C		0.15 - 0.25	0.25 - 0.35	0.4 - 0.6	0.6 - 0.8	0.9 - 1.2

(b)